

FORM PTO-1449 (MODIFIED)

ATTORNEY DOCKET NO.
SP01-300SERIAL NO.
To Be AssignedLIST OF PATENTS AND
PUBLICATIONS
FOR APPLICANTS INFORMATION
DISCLOSURE STATEMENT

APPLICANT Filhaber et al.

FILING DATE: Herewith

GROUP: To Be Assigned

1017 U.S. PTO
10/035358

10/26/01

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
MRCC	AA	5,915,193	6/22/99	Tong et al.	438	455	
MRCC	AB	5,785,874	7/28/98	Eda	216	24	
MRCC	AC	5,932,048	8/3/99	Furukawa et al.	156	153	
MRCC	AD	6,129,854	10/10/00	Ramsey et al.	216	18	
MRCC	AE	6,153,495	11/28/00	Kub et al.	438	459	
AK							

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub-Class	Translation Yes	No
	AL							
	AM							
	AN							

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

MRCC	AO	A. Sayah, D. Solignac, T. Cueni, "Development of novel low temperature bonding technologies for microchip chemical analysis applications," Sensors and Actuators, 84 (2000) pp. 103-108.						
MRCC	AP	P. Rangsten, O. Vallin, K. Hermansson, Y. Backlund, "Quartz-to-Quartz Direct bonding," J. Electrochemical Society, V. 146, N. 3, pp. 1104-1105, 1999).						
MRCC	AQ	H. Nakanishi, T. Nishimoto, M. Kani, T. Saitoh, R. Nakamura, T. Yoshida, S. Shoji, "Condition Optimization, Reliability Evaluation of SiO ₂ -SiO ₂ HF Bonding and Its Application for UV Detection Micro Flow Cell," Sensors and Actuators, V. 83, pp. 136-141, 2000.						
MRCC	AR	A. Yamada, et al., Bonding Silicon wafer to Silicon Nitride With Spin-on Glass Adhesive, Electronics Letters, March 26, 1987, Vol. 23, No. 7.						
MRCC	AS	D.J. Harrison, et al., Micromachining a Miniaturized Capillary Electrophoresis-Based Chemical Analysis System on a Chip, Science 261 (1993) 895-897.						
MRCC	AT	W.P. Maszara, Silicon-on-insulator by Wafer Bonding: A Review, J. Electrochemical Society 138 (1991) 341-347.						
MRCC	AU	D-W. Shin, et al., The Stacking Faults and Their Strain Effect at the Si/SiO ₂ Interfaces of a Directly Bonded SOI (silicon on insulator), Thin Solid Films, V. 346, pp. 169-173, 1999.						
MRCC	AV	Q-Y. Tong, et al., The Role of Surface Chemistry in Bonding of Standary Silicon Wafers, J. Electrochemical Society V. 144, N. 1, pp. 384-389, 1997						

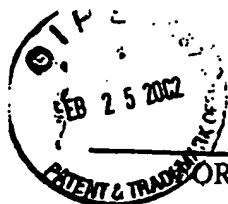
EXAMINER:

Michelle R. Connelly-Cushwa

DATE CONSIDERED:

9/4/03

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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SERIAL NO.

10/035,358

APPLICANT Filhaber et al.

FILING DATE October 26, 2001

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REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Sub- Class	Filing Date if Approp.
	AA						
	AB						
	AC						
	AD						
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	AG						
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	AI						
	AJ						
	AK						

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub- Class	Translation	
							Yes	No
MRCC	AL	52[1977]-78450	7/1/77	Japan	G02B	5/14	X	
	AM							
	AN							
	AO							
	AP							
	AQ							

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

	AR	
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	AT	
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8/7/03

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APPLICANT Filhaber et al.

FILING DATE October 26, 2001

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REFERENCE DESIGNATION				U.S. PATENT DOCUMENTS			
Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
	AA						
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	AI						
	AJ						
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FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Sub-Class	Translation	
							Yes	No
MRCC	AL	P2000-56265A	2/25/00	Japan	G02B	27/28	X	
	AM							
	AN							
	AO							
	AP							
	AQ							

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)		
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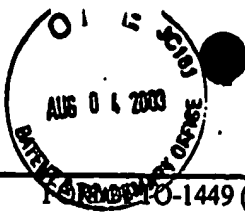
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	APPLICANT: Filhaber et al.	
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REFERENCE DESIGNATION				U.S. PATENT DOCUMENTS			
Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
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	AH						
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FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Sub-Class	Translation Yes No
	AL						
	AM						
	AN						
	AO						
	AP						
	AQ						

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)		
mc	AR	Andreas Plohl et al., Wafer Direct Bonding: Tailoring Adhesion Between Brittle Materials, Materials Science and Engineering, R25 (1999) pp. 1-88.
	AS	
	AT	
	AU	
	AV	
	AW	

EXAMINER: Michelle R. Connelly-Cushwa DATE CONSIDERED: 2/11/04
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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SP01-300

10/035358

APPLICANT :Filhaber, John F., et al.

FILING DATE 10/26/2001

GROUP: 2874

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
mc	AA	4,186,999	2/5/80	Harwood et al	350	96.21	10/25/77
mc	AB	4,407,667	10/4/83	Le Noane et al	65	3.11	7/20/81
mc	AC	4,530,452	7/23/85	Balyasny et al	225	96	8/29/84
mc	AD	4,626,068	12/2/86	Caldwell	350	96.34	7/29/82
mc	AE	5,183,710	2/2/93	Gerbino	428	405	4/23/91
mc	AF	5,451,547	9/19/95	Himi et al	437	225	8/25/92
mc	AG	5,452,122	9/19/95	Tsuneda et al	359	281	8/5/91
mc	AH	5,785,874	7/28/98	Eda	216	24	8/4/95
mc	AI	5,852,622	12/22/98	Meissner et al	372	39	9/11/96
mc	AJ	5,989,372	11/23/99	Momoda et al	156	89.11	5/7/98
mc	AK	6,030,883	2/29/00	Nishimoto et al	438	455	5/20/97
mc	AL	6,048,103	4/11/00	Furukata et al	385	73	6/3/99
mc	AM	6,098,429	8/8/00	Mazabraud et al	65	392	2/4/99
mc	AN	6,178,779	1/30/01	Drouart et al	65	391	3/30/99
mc	AO	6,249,619	6/19/01	Bergmann	385	11	9/17/98
mc	AP	6,275,336	8/14/01	Yoshikawa et al	359	484	7/30/97
mc	AQ	6,359,733	3/19/02	Iwatsuka et al	359	500	8/14/00
mc	AR	6,429,144	8/6/02	Vines et al	438	745	12/28/99
mc	AS	2003/0079823	5/1/03	Sabia	156	99	9/25/02
mc	AT	2003/0079503	5/1/03	Cook et al	65	407	10/26/01

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub-Class	Translation Yes	No
mc	AU	DE2130905	1/11/73	Germany	01	19/56		X
mc	AV	DE19731075	1/21/99	Germany	03	29/00		X
mc	AW	WO01/98225	12/27/01	PCT	03	27/06	X	
mc	AX	WO01/73831	10/4/01	PCT	01	21/304		X
mc	AY	WO00/17698	3/30/00	PCT	02	1/09	X	
mc	AZ	EP1057793	3/13/02	Europe	03	37/027	X	

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*Michelle R. Connolly-Cushwa**2/11/04*

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OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

MC	BA	Arthur Landrock. "Adhesives Technology Handbook." 1985, p. 117-118.
mc	BB	Yoshikawa Hiroki; Japanese abstract of 2002321947; 11/8/02 "Optical Device and Method for Producing the Same"
MC	BC	Furukata; Japanese Abstract of Publication No. 08146351; 6/7/96; "Element for Optical Isolator and its Production"
mc	BD	Ohashi et al; Japanese Abstract of Publication No. 03-115178; 5/16/91; "Method for Joining Aluminum or Aluminum Ceramics by Diffusion".
mc	BE	Onishi et al; "A Novel Temperature Compensation Method for SAW Devices Using Direct Bonding Techniques"; IEEE Ultrasonics Symposium; 1997; pages 227-230.
	AV	
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